

Application Note DA1453x Flash Selector Guide AN-B-088

Abstract

This document presents an overview of supported Flash devices for the DA1453x and DA14585 Bluetooth IC's.

- DA1453x is referring to DA14531-00, DA14531-01, DA14530 and DA14535.

- The DA14531-00 is the main DA14531 device. The -00 is just a new naming to introduce the variant DA14531-01.

- The DA14531-01 is a ROM variant of the main DA14531-00.

- The DA14535 is a DA14531 upgrade.



1 List of Supported Renesas Flash Devices

Table 1: Ordering Information

Memory Size	Flash Device	DA1453x	DA14585
512 kBit	AT25DF512C	V	V
	AT25XE512C	V	V
1 Mbit	AT25DN011	-	V
	AT25DF011	V	V
	AT25XE011	V	V
2 Mbit	AT25EU0021A	V	V
	AT25DF021A	V	V
	AT25XE021A	V	V
4 Mbit	AT25XE041B	V	V
	AT25FF041A	V (1)	V
	AT25XE041D	V (1)	V
	AT45DB041E	-	V
8 Mbit	AT25FF081A	V(1)	V
	AT25XE081D	V (1)	V
32 Mbit	AT25SL321	V	V

Note 1 This requires a secondary loader in OTP for enabling Ultra Deep Power Down mode.

2 List of Supported 3rd Party Flash Devices

Memory Size	Flash Device	Manufacturer	DA1453x	DA14585
512 kBit	MX25R512F	Macronix	V	V
1 Mbit	P25X10U	Puya	V	V
	P25Q10H	Puya	V	V
	GD25WD10CTIG	GigaDevice	V	V
	W25X10CL	Winbond	V	V
2 Mbit	MX25R2035F	Macronix	V	V
	GD25VQ20C	GigaDevice	V	V
	GD25WD20CTIG	GigaDevice	V	V
	W25X20CL	Winbond	V	V
4 Mbit	GD25WD40CTIG	GigaDevice	V	V
	W25X40CL	Winbond	V	V

Table 2: Ordering Information

For additional information related to external memories, please refer to AN-B-072 DA1453x Booting from OTP and Serial Interfaces and AN-B-055 DA14585 interfacing with external memory.

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3 References

- UM-B-117: DA14531 Getting Started with the Pro-Development Kit
- UM-B-165: DA14535 Getting Started with the Pro-Development Kit
- UM-B-119: DA1453x/DA1458x SDK 6 Software Platform Reference: To know more about the software architecture



Revision History

Revision	Date	Description
1.8	13-02-2024	Section 3 and support for DA14535 device added
1.7	31-May-2022	Update Table 1 (Add AT25SL321) and Table 2 (Add W25X40CL)
1.6	24-Jan-2022	Rebranded to Renesas.
1.5	17-11-2021	Update Table 1
1.4	28-09-2021	Update Table 1 (Add AT25EU0021A)
1.3	30-06-2021	Update Hyperlinks in section 1
1.2	15-02-2021	Update Hyperlinks in section 2
1.1	12-11-2020	Update Table 1
1.0	22-10-2020	Initial Release





Status Definitions

Status	Definition
DRAFT	The content of this document is under review and subject to formal approval, which may result in modifications or additions.
APPROVED or unmarked	The content of this document has been approved for publication.

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